

Patent

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Customer No.: 31561
Docket No. 11843-US-PA
Application No.: 10/707,687

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Applicant : Chen et al.
Application No. : 10/707,687
Filed : January 5, 2004
For : CHIP PACKAGE STRUCTURE AND PROCESS FOR
FABRICATING THE SAME
Art Unit : 2822
Examiner : LEWIS, MONICA

TRANSMITTAL LETTER

+1-571-273-8300

(Via fax: 1+3+1 pages)

Assistant Commissioner for Patents
Alexandria, VA 22314

Dear Sir,

Applicants hereby respectfully submit the Supplemental Amendment in 3 pages together with the Replacement Sheet in 1 page.

The Commissioner is authorized to charge any fees required in connection with the filing of this paper to account No.: 50-2620 (Order No.: 11843-US-PA).

Thank you for your assistance in the subject matter. If you have any questions, please feel free to contact me.

Respectfully Submitted,
JIANQ CHYUN Intellectual Property OfficeDate: Dec. 28, 2005By: Belinda Lee
Belinda Lee
Registration No.: 46,863

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In Re Application of:

Chen et al.

Examiner : LEWIS, MONICA

Serial No. : 10/707,687

Art Unit : 2822

Filed : 01/05/2004

Docket No. : 11843-US-PA

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AND PROCESS FOR
FABRICATING THE SAME

No fee is believed to be due. However, the Commissioner is authorized to charge any fees required in connection with the filing of this paper to account No. 50-2620 (Order No. 11843-US-PA).

SUPPLEMENTAL AMENDMENTS

U.S. Patent and Trademark Office
Commissioner for Patents
220 20 th Street South
Customer Window, Mail Stop Amendment
Crystal Plaza Two, Lobby, Room 1B03
Arlington, Virginia 22202

Dear Sir:

Prior to the examination on merits, please amend the above-identified application as follows:

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